

What is claimed is:

1. A copper foil for use in laser beam drilling, comprising a particle layer 0.01 to 3 μm thick which is formed at least on a surface thereof which the laser beam enters by plating
5 said surface with at least one or more kinds of metals comprising copper.
2. The copper foil for use in laser beam drilling according to claim1, further comprising an over-plated coating which is formed on the surface of said particle layer formed by
10 said metal plating without changing the surface configuration.